Product End-of-Life Instructions

Modicon STB Distributed I/O and power modules

Product Range
Modicon STB Distributed I/O and power modules

Marketing Model

Size in mm:
H x L x D : 75 x 128 x 18

Weight in g:
100 to 150
Operations recommended for the end of life treatment

There are several steps to process the products at the end of life so as to recover components, materials or energy:

Reuse ⇔ Separation for special treatment ⇔ Other Dismantling ⇔ Shredding

The components of the products that optimize the recycling performances are listed, identified and located hereunder.

<table>
<thead>
<tr>
<th>Recommendation</th>
<th>Number on drawing</th>
<th>Components</th>
<th>Weight (g)</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>Depollution</td>
<td>1</td>
<td>Printed Circuit Board Assembly (PCBA)</td>
<td>25.4</td>
<td>-</td>
</tr>
<tr>
<td>Dismantling</td>
<td>2</td>
<td>Plastic housing assembly</td>
<td>39.0</td>
<td>-</td>
</tr>
<tr>
<td></td>
<td>3</td>
<td>Plastic base assembly</td>
<td>20.7</td>
<td>-</td>
</tr>
</tbody>
</table>